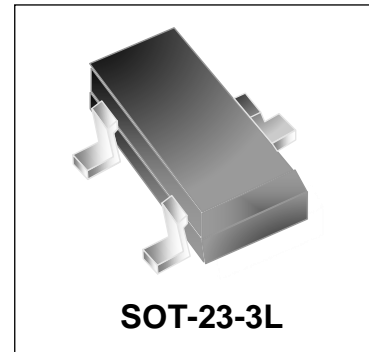


Features

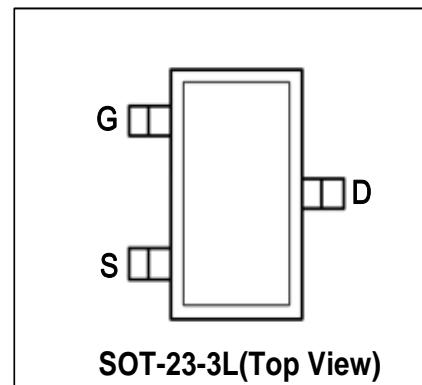
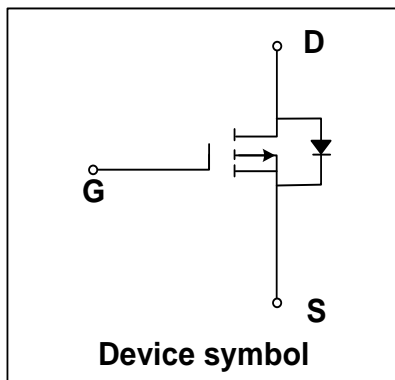
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- Capable doing Cu wire bonding

Applications

- Load Switch
- Portable Equipment and Battery Powered Systems



Schematic & PIN Configuration



Absolute Maximum Rating ($T_{amb}=25^{\circ}\text{C}$ unless otherwise specified)

Rating	Symbol	Value	Units
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	-4.1	A
Pulsed Drain Current ¹	I_{DM}	-20	
Power Dissipation	P_D	0.3	W
Thermal Resistance from Junction to Ambient($t \leq 5s$) ²	$R_{\theta JA}$	417	$^{\circ}\text{C}/\text{W}$
Operating Junction Temperature	T_J	150	$^{\circ}\text{C}$
Storage Temperature	T_{STG}	-55 to 150	$^{\circ}\text{C}$

Electrical Characteristics (T_{amb}=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Static Characteristics						
Drain-Source breakdown voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250μA	-30	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =-24V, V _{GS} =0V	-	-	-1	μA
Gate-Source leakage	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
Gate-Source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =-250μA	-1	-1.4	-3	V
Drain-source on-state resistance ¹	R _{DS(on)}	V _{GS} =-10V, I _D =-4.1A	-	50	60	mΩ
		V _{GS} =-4.5V, I _D =-3.0A	-	68	87	
Forward Trans conductance ¹	g _{fs}	V _{DS} =-5V, I _D =-4A	5.5	-	-	S
Dynamic Characteristics²						
Input capacitance	C _{iss}	V _{GS} =0V ,V _{DS} =-15V , f=1.0MHz	-	700	-	pF
Output capacitance	C _{oss}		-	120	-	
Reverse transfer capacitance	C _{rss}		-	75	-	
Switching Characteristics²						
Turn-on delay time	t _{d(on)}	V _{GS} =-10V, V _{DS} =-15V , R _L =3.6Ω, R _{GEN} =3Ω,	-	8.6	-	ns
Rise time	t _r		-	5.0	-	
Turn-off delay time	t _{d(off)}		-	28.2	-	
Fall Time	t _f		-	13.5	-	

Notes: 1. Pulse test: Pulse width ≤300μs, Duty cycle ≤2%

2. These parameters have no way to verify.

Typical Characteristics

Fig 1. Output Characteristics

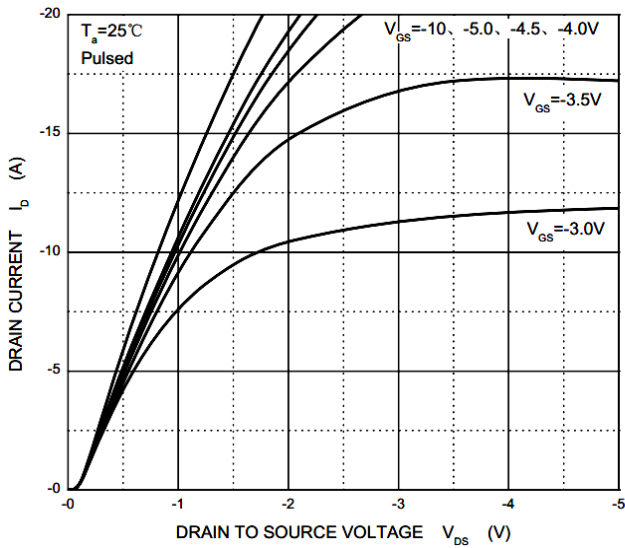


Fig 2. Transfer Characteristics

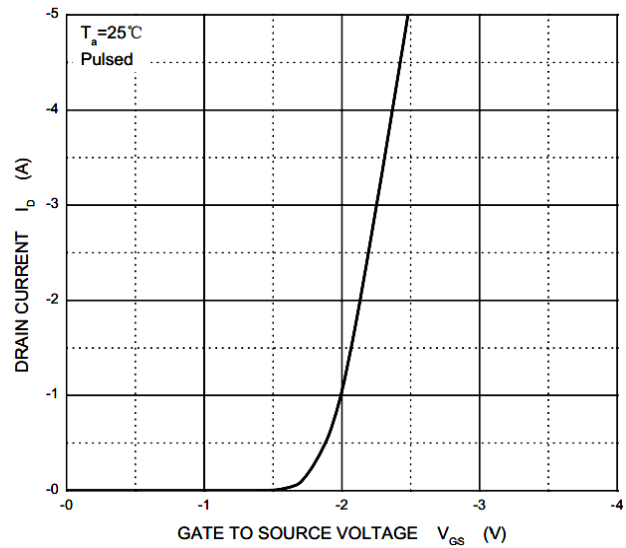


Fig 3. $R_{DS(ON)}$ vs. I_D

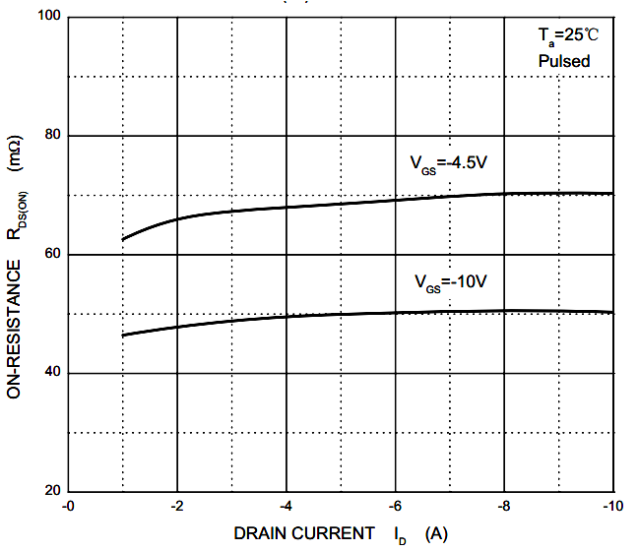


Fig 4. $R_{DS(ON)}$ vs. V_{GS}

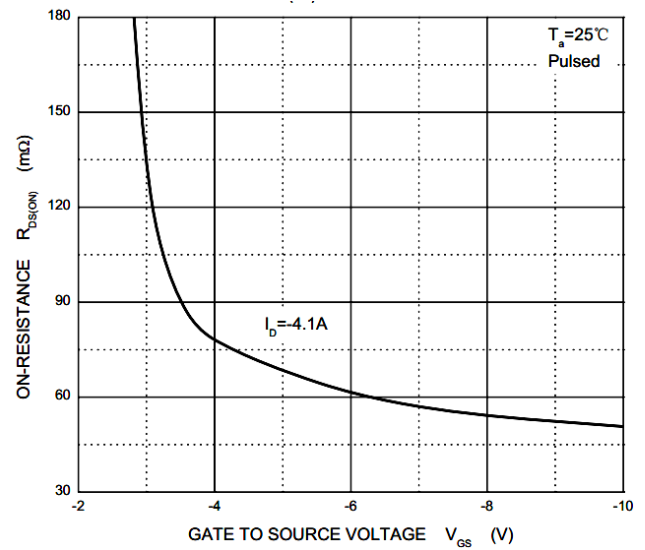
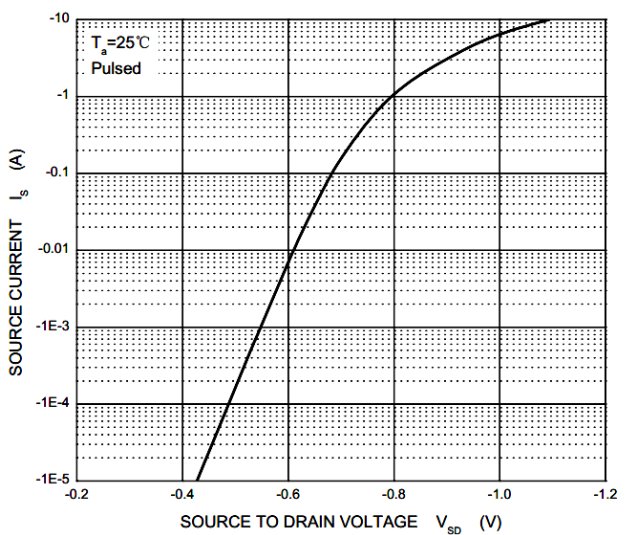


Fig 5. I_s vs. V_{SD}



Outline Drawing – SOT-23-3L

PACKAGE OUTLINE

SOT-23-3L

DIMENSIONS				
SYMBOL	MILLIMETER		INCHES	
	MIN	MAX	MIN	MAX
A	1.05	1.15	0.041	0.045
A1	0.00	0.10	0.000	0.004
b	0.30	0.50	0.012	0.020
c	0.10	0.20	0.004	0.008
D	2.82	3.02	0.111	0.119
E	2.65	2.95	0.104	0.116
E1	1.50	1.70	0.059	0.067
e	0.95 BSC		0.0374 BSC	
e1	1.80	2.00	0.071	0.079
L	0.55	0.75	0.021	0.029
θ	0	8°	0	8°

Unit:mm

Notes

1. Dimensioning and tolerances per ANSI Y14.5M, 1985.
2. Controlling Dimension: Inches
3. Dimensions are exclusive of mold flash and metal burrs.

Marking Codes

Part Number	WM03P41M2
Marking Code	3407

Package Information

Qty: 3k/Reel

CONTACT INFORMATION

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WAYON website: <http://www.way-on.com>

For additional information, please contact your local Sales Representative.

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Specifications are subject to change without notice.
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.
Users should verify actual device performance in their specific applications.